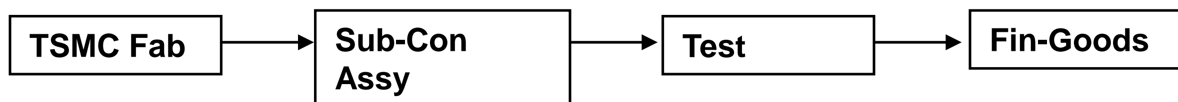
QUALIFICATION RESULTS SUMMARY OF FAB TRANSFER AT ADI PER PCN 17_0142			
TEST	SPECIFICATION	SAMPLE SIZE	RESULTS
High Temperature Operating Life (HTOL)*	JEDEC *JESD22-A108*	**1*77**	**Passed**
Highly Accelerated Stress Test (HAST)*	JEDEC *JESD22-A110*	**1*77**	**Passed**
Autoclave	JEDEC JESD22-A102	**1*77**	**Passed**
Temperature Cycle (TC)*	JEDEC *JESD22-A104*	**1*77**	**Passed**
Early Life Failure (ELF)	MIL-STD-883 *Method 1015*	**3*667**	**Passed**
High Temperature Storage Life (HTSL)	JEDEC *JESD22-A103*	**1*45**	**Passed**
Solder Heat Resistance (SHR)*	*ADI-0049*	**1*30**	**Passed**
Latch-Up	JEDEC *JESD78*	**6**	**Passed**
Electrostatic Discharge *Human Body Model*	ESDA/JEDEC *JDS-001-2011*	**3/voltage**	**Passed**
Electrostatic Discharge *Field-Induced Charged Device Model*	JEDEC *JESD22-C101*	**3/voltage**	**Passed**

*Preconditioned per JEDEC/IPC J-STD-020

Alternate fab source for RS-232 and RS-485/RS-422 Transceiver products. To enable additional wafer fabrication capacity

Current Flow:



Alternate Flow: